# CHEMTRONICS Technical Data Sheet

TDS # SWick

## **Soder-Wick® Desoldering Braid**

## PRODUCT DESCRIPTION

Soder-Wick® offers the state of the art in Soder-Wick® is desoldering technology. designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds faster desoldering than conventional overheating thereby minimizing preventing PCB damage. A full range of sizes and flux types are available, including Rosin, No Clean, unfluxed and a high temperature Lead-Free version. Whatever the requirement, Soder-Wick® has the answer.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized construction for faster wicking and heat transfer
- Halide free
- Minimizes the risk of heat damage to components and circuit boards

## TYPICAL APPLICATIONS

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

# TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Flux Types:
Rosin Grade WW, Type "R"
Patented No Clean
High Temperature No Clean

Specifications:
ANSI/IPC J STD-004
MIL-F-14256 F

No Clean Flux Spec:
MIL-STD-883B

Bellcore TR-NWT-000078 ANSI/IPC J SF818

**Shelflife:** 2 years

| Size# | Width<br>Inches | Color  | Width<br>Metric |
|-------|-----------------|--------|-----------------|
| 1     | .030"           | White  | 0.8mm           |
| 2     | .060"           | Yellow | 1.5mm           |
| 3     | .080"           | Green  | 2.0mm           |
| 4     | .110"           | Blue   | 2.8mm           |
| 5     | .145"           | Brown  | 3.7mm           |
| 6     | .210"           | Red    | 5.3mm           |
| BGA   | -               | Purple | -               |

### STATIC DISSIPATIVE PACKAGING

Soder-Wick<sup>®</sup> SD is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

## **USAGE INSTRUCTIONS**

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick® desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks® Flux Remover Pen and remove soils with a ControlWipes™ absorbent wipe.

# SODER-WICK® IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R NASA-STD-8739.3 DOD-STD-883E, Method 2022 ANSI/IPC J STD-004, Type ROL0 BELLCORE TR-NWT-000078 ANSI/IPC J SF-818

# SODER-WICK® SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A MIL-B-81705C MIL-STD-1686C MIL-HDBK-263B

# TECHNICAL & APPLICATION ASSISTANCE

Chemtronics provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.** 

## **AVAILABILITY**

#### **Series:**

40 Soder-Wick® Lead-Free, SD Bobbin

**50** Soder-Wick<sup>®</sup> Rosin

80 Soder-Wick® Rosin, SD Bobbin

60 Soder-Wick® No Clean, SD Bobbin

**70** Soder-Wick<sup>®</sup> Unfluxed

75 Soder-Wick<sup>®</sup> Unfluxed, SD Bobbin

## VacuPak<sup>™</sup> Packaging

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

#### **HELPFUL HINTS:**

Water Soluble Users: Use Soder-Wick® Unfluxed 70 or 75 Series to dip in water soluble flux and then desolder normally.

**Ball Grid Array:** Use Soder-Wick<sup>®</sup> BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

**NOTE:** This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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# AMEYA360 Components Supply Platform

## **Authorized Distribution Brand:**

























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